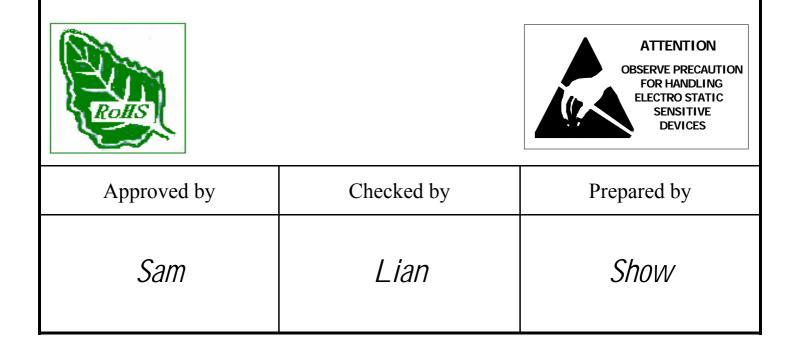
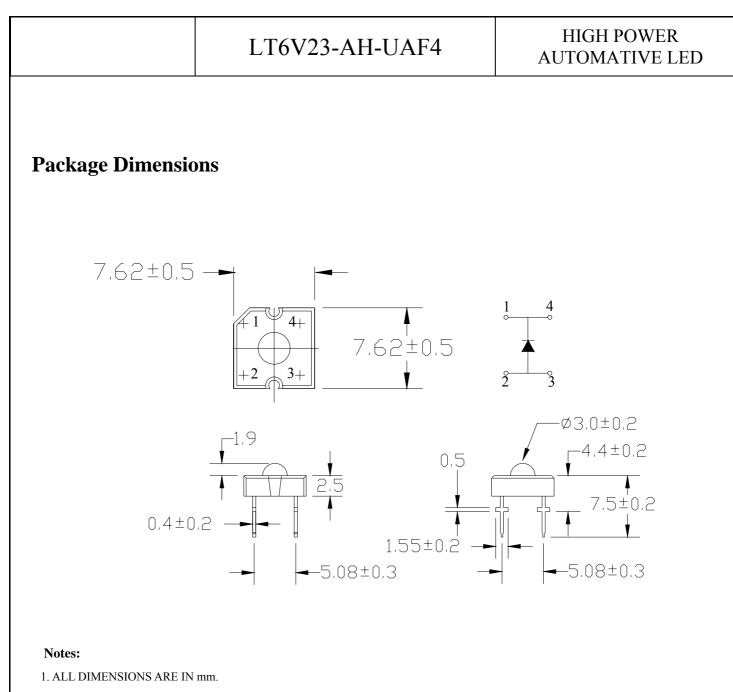
SPECIFICATION

PART NO. : LT6V23-AH-UAF4 HIGH POWER AUTOMATIVE LED





2. TOLERANCE IS ± 0.25 mm UNLESS OTHERWISE NOTED.

Description

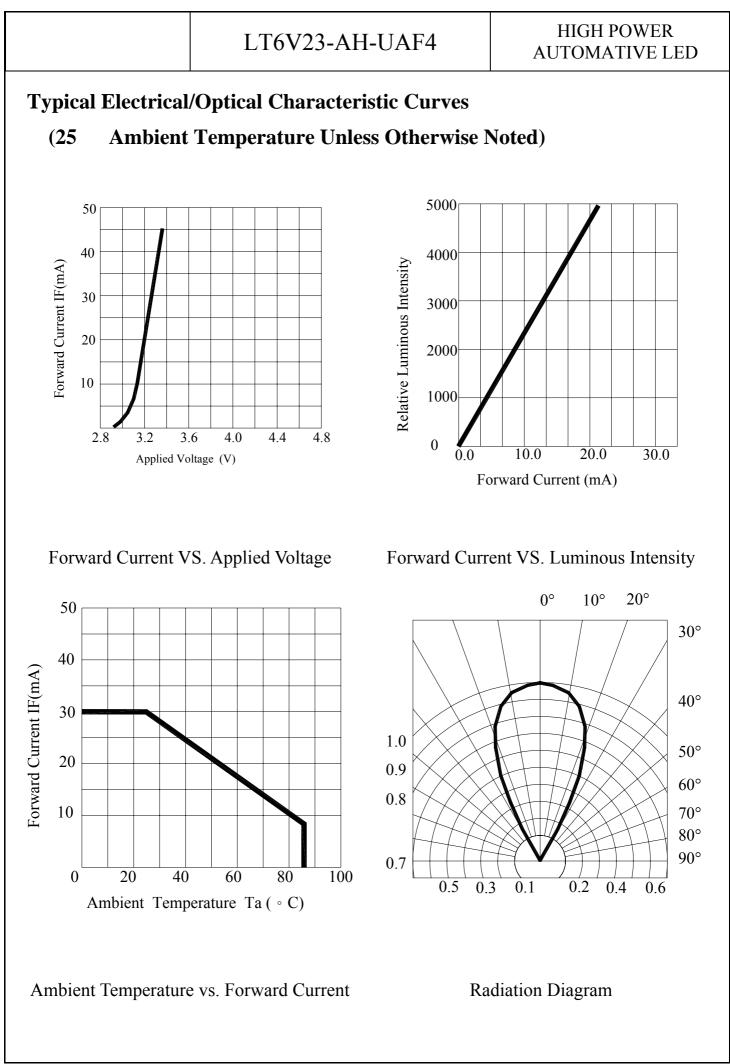
Part No.	LED Ch		
	Material	Emitting Color	Lens Color
LT6V23-AH-UAF4	InGaN/Sapphire	True Green	Water Clear

Absolute Maximum Ratings at Ta=25

Parameter	Symbol	Rating	Unit	
Power Dissipation	Pd	120	mW	
Reverse Voltage	VR	5	V	
D.C. Forward Current	If	30	mA	
Peak Current(1/10Duty Cycle,0.1ms Pulse Width.)	If(Peak)	Peak) 100		
Operating Temperature Range To		-25 to +85		
Storage Temperature Range	Tstg40 to +100			
Lead Soldering Temp. (1.6mm from body) for 5 seconds.	260			
Electric Static Discharge Threshold (HBM)	300	V		

Electrical and Optical Characteristics:

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity	Iv	If=20mA	2750	4600		mcd
Forward Voltage	Vf	If=20mA		3.2	4.0	V
Peak Wavelength	λΡ	If=20mA				nm
Dominant Wavelength	λD	If=20mA		525		nm
Reverse Current	Ir	Vr=5V			50	μA
Viewing Angle	2 1/2	If=20mA		50		deg
Spectrum Line Halfwidth	Δλ	If=20mA		35		nm



HIGH POWER AUTOMATIVE LED

Precautions:

TAKE NOTE OF THE FOLLOWING IN USE OF LED

1. Temperature in use

Since the light generated inside the LED needs to be emitted to outside efficiently, a resin with high light transparency is used; therefore, additives to improve the heat resistance or moisture resistance (silica gel, etc) which are used for semiconductor products such as transistors cannot be added to the resin.

Consequently, the heat resistant ability of the resin used for LED is usually low; therefore, please be careful on the following during use.

Avoid applying external force, stress, and excessive vibration to the resins and terminals at high temperature. The glass transition temperature of epoxy resin used for the LED is approximately 120-130%%DC.

At a temperature exceeding this limit, the coefficient of liner expansion of the resin doubles or more compared to that at normal temperature and the resin is softened.

If external force or stress is applied at that time, it may cause a wire rupture.

2. Soldering

Please be careful on the following at soldering.

After soldering, avoided applying external force, stress, and excessive vibration until the products go to cooling process (normal temperature), <Same for products with terminal leads>

(1) Soldering measurements:

Distance between melted solder side to bottom of resin shall be 1.6mm or longer.

- Solder dip: Preheat: 90%%dC max. (Backside of PCB), Within 120 seconds
 Solder bath: 250%%dC max. (Solder temperature), Within 5 seconds
- (3) Soldering iron : 250%%dC max. (Temperature of soldering iron tip), Within 3 seconds
- 3. Insertion

Pitch of the LED leads and pitch of mounting holes need to be same

4. Others

Since the heat resistant ability of the LED resin is low, SMD components are used on the same PCB, please mount the LED after adhesive baking process for SMD components. In case adhesive baking is done after LED lamp insertion due to a production process reason, make sure not to apply external force, stress, and excessive vibration to the LED and follow the conditions below.

Baking temperature: 120%%dC max. Baking time: Within 60 seconds

If soldering is done sequentially after the adhesive baking, please perform the soldering after cooling down the LED to normal temperature.

HIGH POWER AUTOMATIVE LED

ENCASED TYPE

